ABSTRACT

The invention concerns a method for evaluation of heterogeneous deformations in a first wafer (110), the first wafer being bonded by molecular adhesion to a second wafer (120). This evaluation method comprises a step of surveying a plurality of measurement points, each of the measurement points being locally representative of the level of the surface of the first wafer; a step of determination of a surface profile of the first wafer passing through a plurality of measurement points; a step of processing the surface profile of the first wafer to determine therefrom a characteristic magnitude; and a step of evaluation of a level of heterogeneous deformations in the first wafer as a function of the characteristic magnitude.

The invention further concerns a device (147) enabling evaluation of such heterogeneous deformations.

(Figure 7)